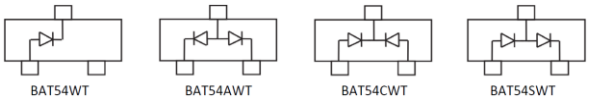
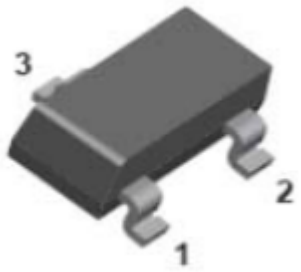
Schottky Barrier Diode





Features

- Moisture sensitivity level 1
- Reverse voltage: 30V
- Average forward current : 200mA

Application

- High frequency and low voltage rectifier

Mechanical data

- **Package**: SOT-323
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102

■ **Maximum Ratings** (T_a=25℃ Unless otherwise specified)

Parameter	Symbol	Unit	Value	
Device marking code			BAT54WT	KL5
			BAT54AWT	KL6
			BAT54CWT	KL7
			BAT54SWT	KL8
Repetitive peak reverse voltage	V_{RRM}	V	30	
Forward current, per leg	I_F	mA	200	
Non-repetitive surge peak forward current @ t=8.3ms half-sine wave	I_{FSM}	A	0.6	
Non-repetitive surge peak forward current @ t=1ms square wave			0.6	
Repetitive Peak Forward Current@ tp=1ms, δ=0.25	I_{FRM}	A	0.3	
Power dissipation	P_D	mW	200	
Junction temperature	T_J	℃	-55 to +125	
Storage temperature	T_{STG}	℃	-55 to +125	

■ Electrical Characteristics (Ta=25℃ Unless otherwise specified)

Parameter	Symbol	UNIT	Conditions	Min	Typ	Max
Reverse voltage	V_R	V	I_R=0.1mA	30		
Forward voltage	V_{F1}	V	I_F=0.1mA			0.24
	V_{F2}	V	I_F=1mA			0.32
	V_{F3}	V	I_F=10mA			0.4
	V_{F4}	V	I_F=30mA			0.5
	V_{F5}	V	I_F=100mA			1
Reverse leakage current	I_R	uA	V_R=25V			2
Junction capacitance	Cj	pF	V_R=1.0V,f=1MHz		10	
Reverse recovery time	Trr	ns	I_F=I_R=10mA, Irr=0.1*I_R,R_L=100Ω			5

■ Thermal Characteristics

Parameter	Symbol	Unit	Value
Thermal resistance, junction-to-ambient	$R_{\theta J-A}$(1)	℃/W	500
Thermal resistance, junction-to-case	$R_{\theta J-C}$(1)	℃/W	400

Note:

（1）Device mounted on PCB, single-sided copper，with standard footprint

■Characteristics

Fig 1：P_D-Ta Curve

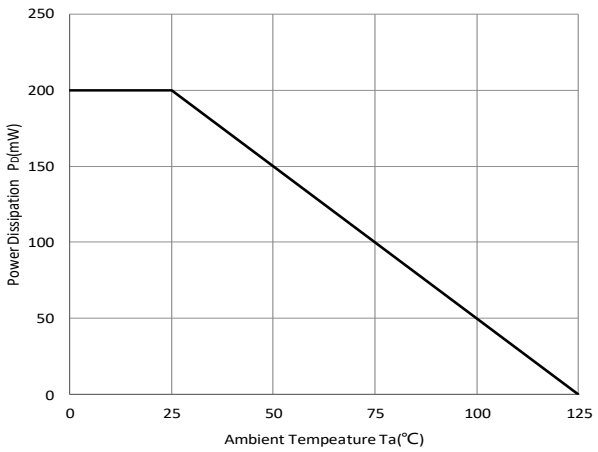


Fig 2：Capacitance Capability

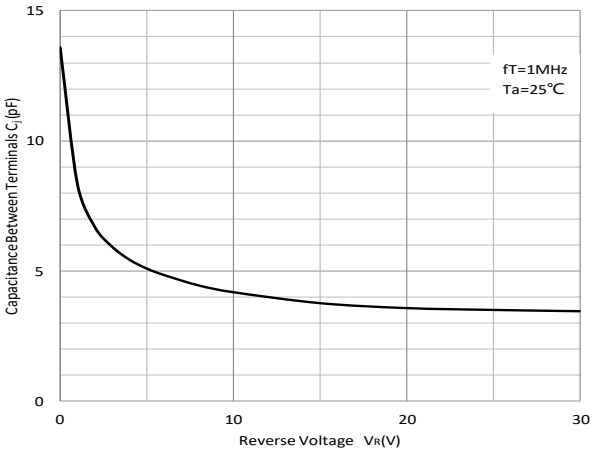


Fig 3：Typical Forward Characteristics

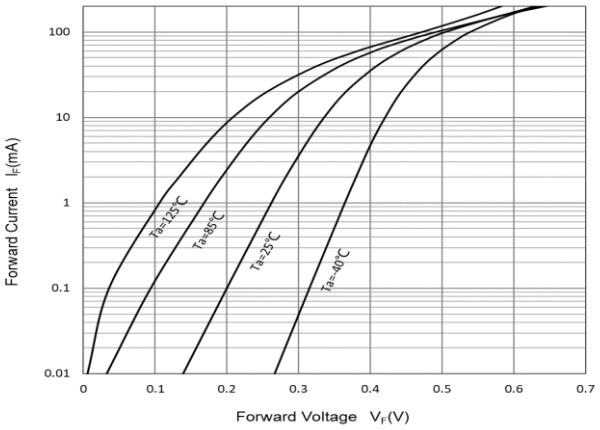
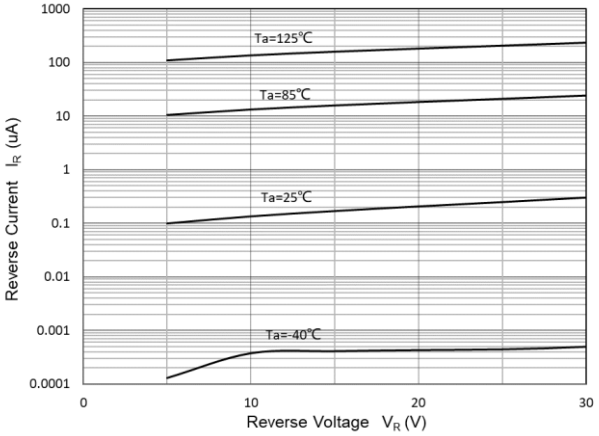


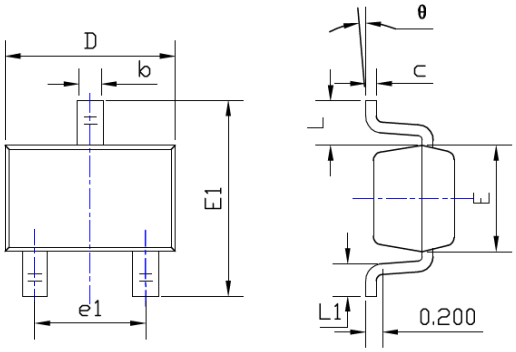
Fig 4：Typical Reverse Characteristics



■Ordering Information

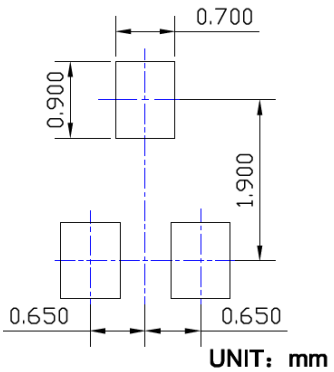
Preferred P/N	Packing code	Unit weight(g)	Minimum package(pcs)	Inner box quantity(pcs)	Outer carton quantity (pcs)	Delivery mode
BAT54WT THRU BAT54SWT	F2	Approximate 0.005	3000	30000	120000	7" reel

■ Outline Dimensions



DIMENSIONS				
SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.043	0.900	1.100
A1	0.000	0.004	0.000	0.100
A2	0.035	0.039	0.900	1.000
b	0.006	0.016	0.150	0.400
c	0.004	0.010	0.100	0.250
D	0.071	0.087	1.800	2.200
E	0.045	0.053	1.150	1.350
E1	0.085	0.096	2.150	2.450
e	0.026TYP		0.650TYP	
e1	0.047	0.055	1.200	1.400
L	0.021REF		0.525REF	
L1	0.010	0.018	0.260	0.460
θ	0°	8°	0°	8°

■ Suggested Pad Layout



Note:
1. All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位，除非另有说明]
2. General tolerances: ±0.10mm unless otherwise specified.
[通用公差为±0.10mm，除非另有说明]
3. Dimensions and tolerances per ASME Y14.5M-2018.
[尺寸和公差遵循 ASME Y14.5M-2018 标准]
4.All dimensions shown are exclusive of burrs and gate residues.
Burrs and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
5.Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
6.Dimensions D and E are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[D和E是塑封体的外部极限尺寸，不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺，但是包含了包封错位的最大尺寸]
7.Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面，共面性最大为0.1mm]

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